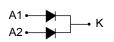


# 150 V power Schottky rectifier





#### **Features**

- · High junction temperature capability
- · Low leakage current
- · High voltage capabilities
- · Low thermal resistance
- · High frequency operation
- Avalanche specification
- ECOPACK<sup>®</sup>2 compliant

### **Applications**

- Switching diode
- SMPS
- DC/DC converter
- · Telecom power

### **Description**

This dual center tab Schottky rectifier is suited for high frequency switched mode power supplies.

Packaged in TO-220AB, the STPS60150C combines high current rating and low volume to enhance both reliability and power density of the application.

Product status			
STPS60150C			
Product summary			
I <sub>F(AV)</sub> 2 x 30 A			
V <sub>RRM</sub>	150 V		
T <sub>j(max.)</sub>	175 °C		
V <sub>F(typ.)</sub>	0.72 V		



### 1 Characteristics

Table 1. Absolute ratings (limiting values, per diode at 25 °C, unless otherwise specified)

Symbol	mbol Parameter				Unit
$V_{RRM}$	Repetitive peak reverse voltage			150	V
I <sub>F(RMS)</sub>	Forward rms current			60	Α
	A	T <sub>C</sub> = 145 °C	Per diode	30	
I <sub>F(AV)</sub>	Average forward current, $\delta$ = 0.5, square wave	T <sub>C</sub> = 135 °C	Per device	60	Α
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinu	270	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 10 μs, T <sub>j</sub> =	1245	W	
T <sub>stg</sub>	Storage temperature range			-65 to +175	°C
Tj	Maximum operating junction temperature <sup>(1)</sup>			+175	°C

<sup>1.</sup>  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	ymbol Parameter		Value	Unit	
Symbol	Fatattietei	Falanietei		Offic	
D .	Lucation to	Per diode	1.0	°C/W	
R <sub>th(j-c)</sub>	Junction to case	Total	0.7	C/VV	
R <sub>th(c)</sub>	Coupling		0.4	°C/W	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_{j \text{ (diode1)}} = P_{\text{(diode1)}} x R_{\text{th(j-c)}} \text{ (per diode)} + P_{\text{(diode2)}} x R_{\text{th(c)}}$ 

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
L (1) Decrease leads	Povorco logicado gurrent	T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$	-	3	15	μA
'R`	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 125 °C		-	3	10	mA
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 30 A	-		0.94	V
V <sub>F</sub> <sup>(2)</sup>	Fanyard valtage drap	T <sub>j</sub> = 125 °C		-	0.72	0.76	
V <sub>F</sub> <sup>(2)</sup> Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 60 A	-	0.97	1.05	V	
		T <sub>j</sub> = 125 °C	IF - 00 A	-	0.86	0.92	

- 1. Pulse test:  $t_p = 5$  ms,  $\delta < 2\%$
- 2. Pulse test:  $t_p$  =380  $\mu$ s,  $\delta$  < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.6 \times I_{F(AV)} + 0.0053 \times I_{F}^{2} (RMS)$ 

For more information, please refer to the following application notes related to the power losses :

· AN604: Calculation of conduction losses in a power rectifier

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0

5

10

AN4021: Calculation of reverse losses on a power diode

### 1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (per diode)

P<sub>F(AV)</sub>(W)

5

0

F(AV)(A)

F(AV)(A)

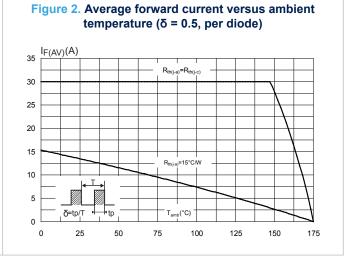


Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j$ = 125 °C)

15

20

25

30

35

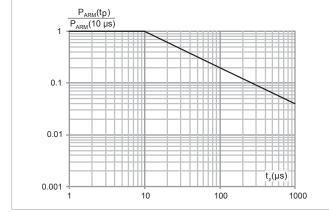
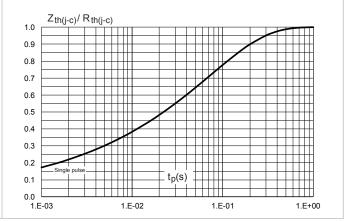


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

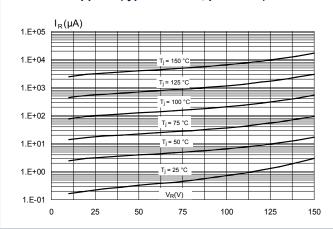


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

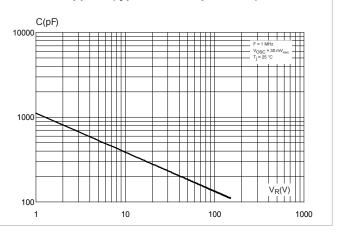
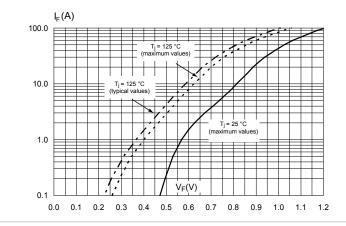


Figure 7. Forward voltage drop versus forward current (per diode)



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# 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

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### 2.1 TO-220AB package information

• Epoxy meets UL 94,V0

Cooling method: by conduction (C)
 Recommended torque value: 0.55 N·m

• Maximum torque value: 0.70 N·m

Figure 8. TO-220AB package outline

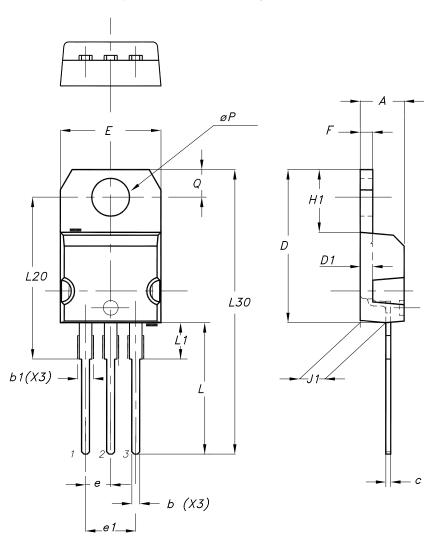


Table 4. TO-220AB package mechanical data

	Dimensions				
Ref.	Millimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
Α	4.40	4.60	0.173	0.181	
b	0.61	0.88	0.240	0.035	
b1	1.14	1.55	0.045	0.061	

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	Dimensions				
Ref.	Millim	Millimeters		nes	
	Min.	Max.	Min.	Max.	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27	typ.	0.050	typ.	
E	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40 typ.		0.646 typ.		
L30	28.90 typ.		1.138 typ.		
θР	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	



# 3 Ordering information

Table 5. Order code

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS60150CT	STPS60150CT	TO-220AB	1.95 g	50	Tube

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# **Revision history**

Table 6. Document revision history

Date	Revision	Changes
19-Oct-2004	1	First issue.
01-Jun-2018	2	Updated PARM value and removed "Normalized avalanche power derating" curves.

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